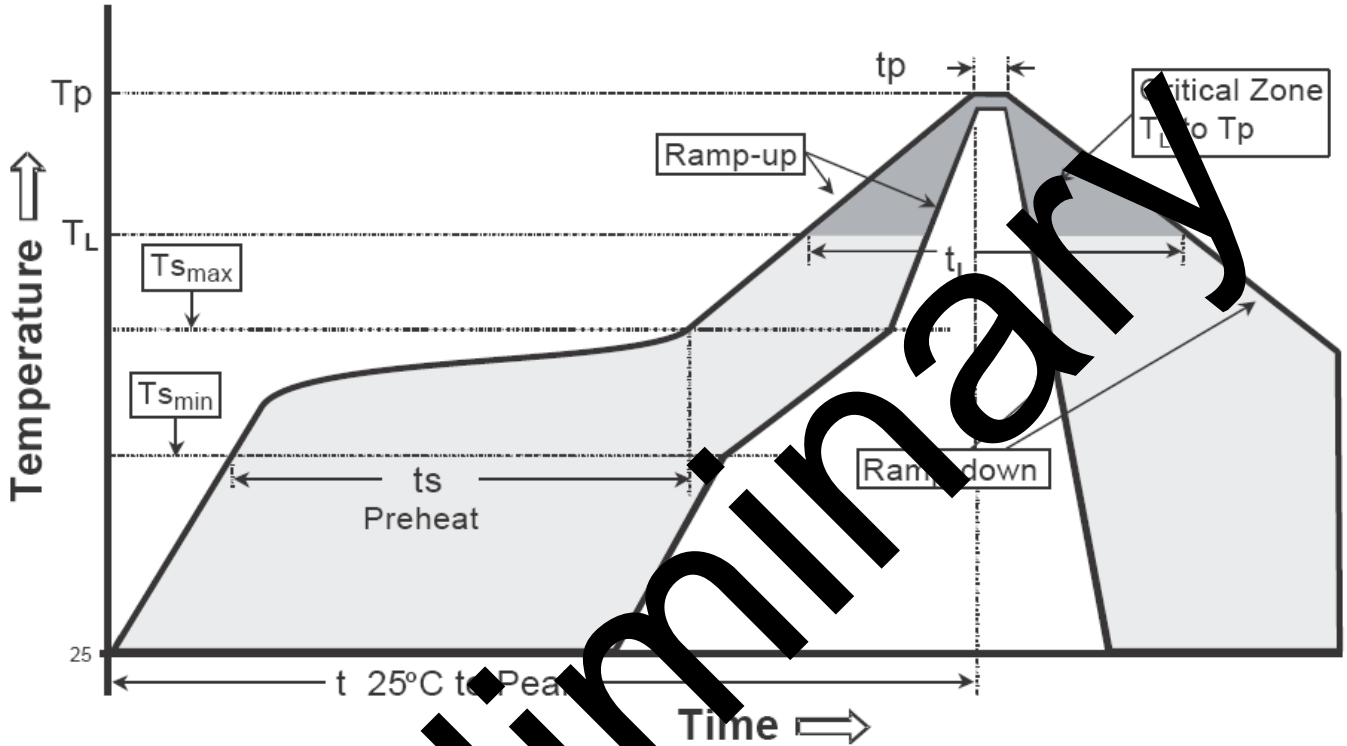


Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn/Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T_{Smax} to T_P)	3°C/second max.	3°C/second max.
Preheat		
-Temperature (T_{Smin})	100°C	150°C
-Temperature Max (T_{Smax})	150°C	200°C
-Time (t_{Smin} to t_{Smax})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T_L)	183°C	217°C
-Time (t_L)	60-150 seconds	60-150 seconds
Peak Temperature (T_P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature (t_p)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note:

- All temperatures refer to topside of the package, measured on
- For devices mounted on FR-4 PCB of 1.6mm or equivalent grade PCB. If other grade PCB is used, care should be taken to match the coefficients of thermal expansion between components and PCB. If they are not matched well, the solder joints may crack or the bodies of the parts may crack or shatter as the assembly cools.